RX74M Group

Handbook for RX74M

Introduction

This document compiles useful information for each stage of device selection, development, and Mass production. You can also select what you need for your application from our rich selection of application notes that describe how to use a peripheral function, example applications, how to create a program, and more.

Please utilize these information, materials and application notes as a handbook when developing.

Target Device

RX74M Group

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1. The table of information and materials needed for Device Selection, Development and Mass production

1.1 Step1: Device Selection

This section summarizes the information that is useful for the preliminary survey phase (Step1-1) and for the evaluation phase of device performance and features (Step1-2) when selecting the device.

1.1.1 Step1-1: Preliminary survey phase

#	Item	Content	Link
1	Hardware information	Datasheet	Doc
2		RX Family Brochure	Doc
3	Products & Solutions	Video & blog	Web site
4		Product deatures, Application block diagram(Winning combination)	Web site
5	Product longevity program (PLP)	Overview of product longevity program (PLP)	Web site
6		Product selection (product selector) Note: Refer to Longevity column in the chart.	Web site
7	Product Specification Comparison	RX Family Product Selector	Web site
8		Industrial Networks Brochure	Doc
9		Differences of specification among RX products	Doc
10		[SH/H8/H8S/H8SX/M16C/V850] → RX microcontroller migration guide	Doc
11		Design guide for migration between RX family differences in package external form	Doc

1.1.2 Step1-2: Evaluation phase of device performance and features

#	Item	Content	Link
User's Manual / Documentation			
1	Hardware information	User's manual: Hardware	Doc
2		RX family hardware manual guidance - electrical characteristics (how to read user's manual: hardware)	Doc
3		RX family hardware manual guidance - peripheral functions (how to read user's manual: hardware)	Doc
4		Technical update (errata information)	Web site
5		Product change notice (PCN)	Web site
6		Part number guide for RX family product (the meaning of character in part number)	Doc
7		Semiconductor reliability handbook	Doc
8		RELIABILITY REPORT	Doc
9		RoHS Note: Please refere to "RoHS" colmun on the respective part number of the product options.	Web site
10	Software information		Doc
Evaluation board			
11	Evaluation board (for general purpose)	Evaluation Kit	Web site
12	Solution board	Renesas flexible motor control kit (CPU board + inverter board + communication board)	Web site
13		CPU board	Web site
Evaluation environment (set up method)			
14	Setup method	Getting started with the RX family development environment	Web site
15	Software tool	Development tools for RX family	Web site
16		Software environment (OS, middleware, drivers)	Web site
17		RX Flexible Software Package (FSP)	Web site
18		Guide for Migration to RX FSP	Doc
Solution			
19	Security	RX Family Security Solutions	Web site
20		Security key management tool manual	Web site
21	GUI	Graphical user interface (GUI) solutions	Web site
22	Functional safety	Functional safety solutions for Industrial automation	Web site
23		Functional safety solution for industrial automation	Doc
24		Introduction to Renesas functional safety for industrial appliance(video)	Web site
Training			

#	Item	Content	Link
25	Training information	How to use tools and solutions (video clips)	Web site
26		CC-RX compiler tutorial - How to use trigonometric function unit (TFU) of RX	Web site
Partner			
27	Partner information	Partner products (trusted technology partners that deliver commercial-grade building blocks)	Web site

1.2 Step2: Product Design Development

This section summarizes useful information for product design and development.

#	Item	Content	Link
1	Board Design	Hardware design guide	Doc
2		Design guide for main clock circuit and Sub-Clock circuit	Doc
3		Notes regarding high-temperature operation	Doc
4		Guidelines for full-speed USB2.0 board design	Doc
5		Ethernet hardware design guide	Doc
6		CAD Model Note: When you click the link in the CAD model column in the "Product Options" table on the product page, the CAD model information for each part# is displayed.	Web site
7		board simulation model (IBIS) *	Web site
8		Setting pins function in Smart configurator for FSP Note: Please refer to the "Pin Settings" section of RX Smart Configurator for FSP User's Guide: e² studio	Web site
9		Resonator and matching circuit information	Doc
10		Package information (package outline information, mount manual, etc.)	Web site
11		Board design guideline for BGA products	Doc

* It requires My Renesas account to access the content.

1.3 Step3: Mass Production

#	Item	Content	Link
1	Writing a program	PG-FP6	Web site
2		Renesas flash programmer (GUI tool for PC)	Web site
3	Firmware update	Renesas Boot Firmware Application note	Doc
4	Inspection	Boundary Scan Description Language (BSDL) file *	Web site

1.4 Supportive information

Get help from our technical staff and community.

#	Item	Content	Link
1	Support information	FAQ (frequently asked inquiries)	Website
2		RX forum (community)	Website
3		Ask technical/sales support(support tickets)	Website

2. Highlighted Application Notes

This part presents the main application notes for this product. In addition to this list, many more application notes and sample codes are available on the product website <www.renesas.com/RX74M> for your reference. (Note: To access the content of sample code, My Renesas account is required.)

#	Item	Content	Link
1	System design	RX Family Application Design Using the RX74M First Stage Bootloader Application note	Doc
2		RX Family Application Design Using the RX74M First Stage Bootloader Sample code	Sample
3	Motor and Inverter Control	Sensorless vector control of a permanent magnet synchronous motor Application note	Doc
4		Sensorless vector control of a permanent magnet synchronous motor Sample code	Sample
5		Vector control for permanent magnet synchronous motor with encoder Application note	Doc
6		Vector control for permanent magnet synchronous motor with encoder Sample code	Sample
7		Sensorless vector control for permanent magnetic synchronous motor - 1shunt current detection Application note	Doc
8		Sensorless vector control for permanent magnetic synchronous motor - 1shunt current detection Sample note	Sample
9		Vector control for permanent magnet synchronous motor with encoder (algorithm)	Doc
10		Sensor less vector control for permanent magnet synchronous motor (algorithm)	Doc
11	GUI	QE for display GUI display application development guide using serial connection LCD	Doc
12		GUI sample program using serial LCD and emWin library Application note	Doc
13		GUI sample program using serial LCD and emWin library Sample code	Sample
14		Module for image rendering (emWin) Application note	Doc
15		Module for image rendering (emWin) Sample code	Sample
16	Industrial network	EK-RX74M EtherNet/IP Sample Program Package Guide Application note	Doc
17		EK-RX74M EtherNet/IP Sample Program Package Guide Sample code	Sample
18		EtherCAT Sample Program Package Guide Application note	Doc
19		EtherCAT Sample Program Package Guide Sample code	Sample
20		EtherCAT Sample Program Package Guide Application note	Doc

#	Item	Content	Link
21	Security	Injecting and Updating Secure User Keys Application note	Doc
22		Injecting and Updating Secure User Keys Sample code	Sample
23		Device Lifecycle Management Application note	Doc

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Mar. 6,2026	-	First edition issued

This handbook incorporates information available as of its publication date. For the most up-to-date details, please refer to the product page on our official website: <www.renesas.com/RX74M>

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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